

From: Paul Dominik <pdominik@futurrex.com>

Subject: Technical Information on NR2-8000P, NR21-20000P, RD6 and RR41.

Dear Prof. Levey:

Please find attached Technical Information on Negative Resists NR2-8000P and NR21-20000P, Resist Developer RD6 and Resist Remover RR41.

NR2-8000P and NR21-20000P are capable of covering thickness range from 5-200  $\mu\text{m}$  and are compatible with plating baths reaching pH of 10.

Because Cu surface reacts with photoacid in chemically amplified resists such as negative resists from Futurrex, it is recommended to apply TiW or Ti film as seed layer in plating on Cu.

Unlike other chemically amplified negative resists, NR2-8000P and NR21-20000P are compatible with patterning directly on Cu. Exposure energy on Cu surface is four times higher than exposure energy on Si.

Sincerely,  
Paul Dominik, PhD